



Material Content Data Sheet



Sales Product Name		IPB180N06S4-H1		Issued		1. August 2018		
MA#		MA001038292						
Package		PG-TO263-7-3		Weight*		1527.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.427	0.68	0.68	6826	6826
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	iron	7439-89-6	0.803	0.05		525	
	non noble metal	copper	7440-50-8	801.714	52.47	52.54	524802	525485
	non noble metal	aluminium	7429-90-5	12.334	0.81	0.81	8074	8074
wire	non noble metal	aluminium	7429-90-5	12.334	0.81	0.81	8074	8074
encapsulation	organic material	carbon black	1333-86-4	8.647	0.57		5660	
	plastics	epoxy resin	-	95.119	6.23		62265	
	inorganic material	silicondioxide	60676-86-0	472.714	30.94	37.74	309439	377364
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8063	8063
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	176	177
solder	non noble metal	tin	7440-31-5	0.134	0.01		88	
	noble metal	silver	7440-22-4	0.168	0.01		110	
	non noble metal	lead	7439-92-1	6.412	0.42	0.44	4197	4395
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	6.95	6.96	69525	69616
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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